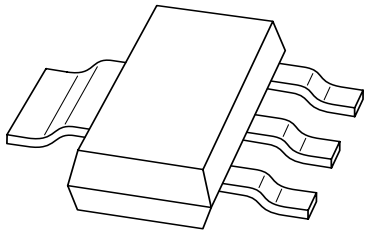


# DATA SHEET



## **BF723** PNP high-voltage transistor

Product data sheet  
Supersedes data of 1996 Dec 05

1999 Apr 21

# PNP high-voltage transistor

**BF723**

## FEATURES

- Low feedback capacitance.

## APPLICATIONS

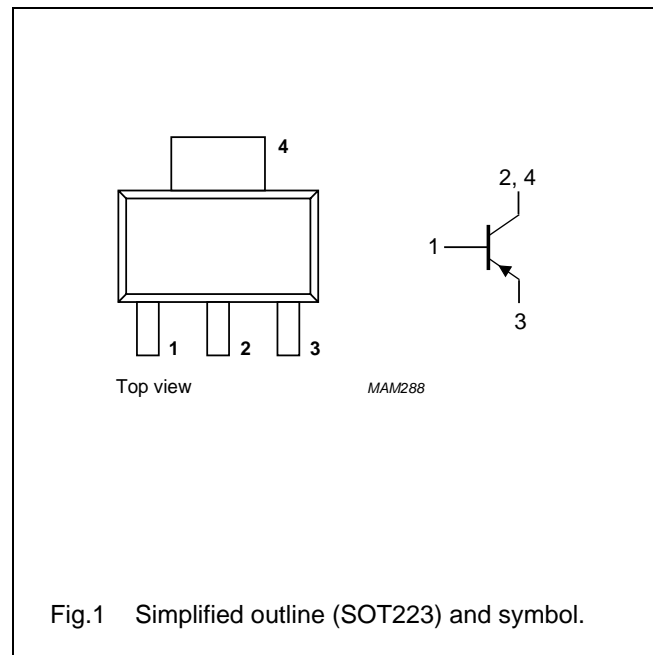
- Class-B video output stages of colour television receivers
- General purpose high voltage circuits.

## DESCRIPTION

PNP transistor in a SOT223 plastic package.  
NPN complement: BF722.

## PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter



## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	–250	V
$V_{CEO}$	collector-emitter voltage	open base	–	–250	V
$V_{EBO}$	emitter-base voltage	open collector	–	–5	V
$I_C$	collector current (DC)		–	–100	mA
$I_{CM}$	peak collector current		–	–200	mA
$I_{BM}$	peak base current		–	–100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^\circ\text{C}$ ; note 1	–	1.2	W
$T_{stg}$	storage temperature		–65	+150	$^\circ\text{C}$
$T_j$	junction temperature		–	150	$^\circ\text{C}$
$T_{amb}$	operating ambient temperature		–65	+150	$^\circ\text{C}$

## Note

1. Device mounted on printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm<sup>2</sup>. For other mounting conditions, see “Thermal considerations for SOT223 in the General Part of associated Handbook”.

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## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	106	K/W
$R_{th\ j-s}$	thermal resistance from junction to soldering point	note 1	25	K/W

## Note

1. Device mounted on printed-circuit board, single sided copper, tinned, mounting pad for collector 1 cm<sup>2</sup>.  
For other mounting conditions, see "Thermal considerations for SOT223 in the General Part of associated Handbook".

## CHARACTERISTICS

$T_j = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = -200\text{ V}$	–	–10	nA
		$I_E = 0; V_{CB} = -200\text{ V}; T_j = 150\text{ °C}$	–	–10	μA
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = -5\text{ V}$	–	–50	nA
$h_{FE}$	DC current gain	$I_C = -25\text{ mA}; V_{CE} = -20\text{ V}$	–50	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -30\text{ mA}; I_B = -5\text{ mA}$	–	–0.6	V
$C_{re}$	feedback capacitance	$I_C = i_c = 0; V_{CE} = -30\text{ V}; f = 1\text{ MHz}$	–	2.5	pF
$f_T$	transition frequency	$I_C = -10\text{ mA}; V_{CE} = -10\text{ V}; f = 100\text{ MHz}$	60	–	MHz

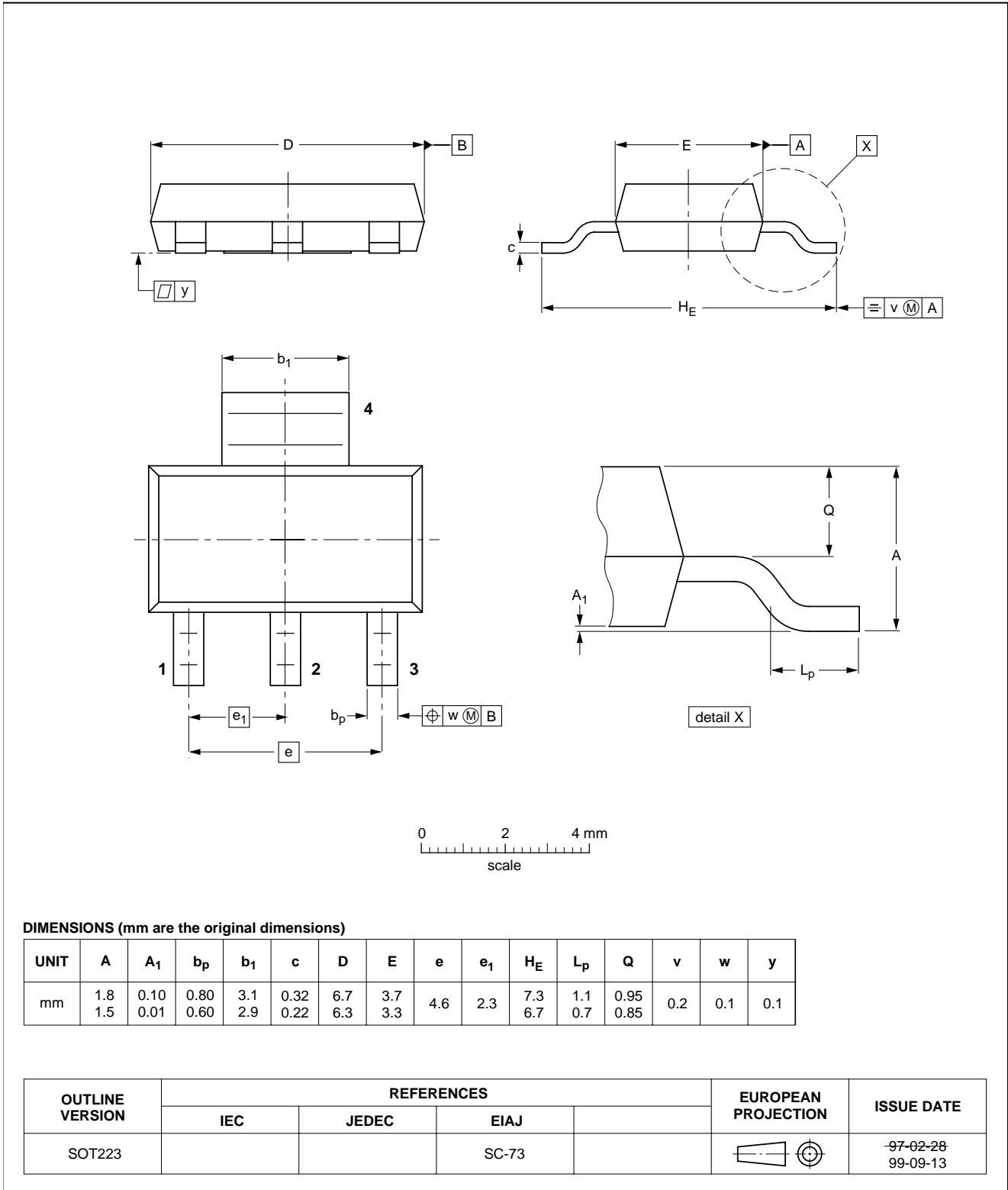
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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 4 leads

SOT223



## PNP high-voltage transistor

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## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

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